METHOD OF DIE BONDING ELECTRONIC COMPONENT AND DIE BONDING APPARATUS THEREFOR

ABSTRACT

A method of die bonding electronic components, comprising the steps of:

providing a dicing tape 17 comprising at least one layer of shrink film and a pressure sensitive adhesive layer;

mounting a wafer on the dicing tape so that the wafer is stuck thereto by the pressure sensitive adhesive layer;

dicing the wafer so that the wafer is cut apart into a multiplicity of chips 16;

disposing the dicing tape 17 having the multiplicity of chips stuck thereto on a table equipped with heating means, and shrinking the shrink film forming part of the dicing tape by the heating means 3,7 so that an area of adhesion and adhesive strength between the chips and the adhesive layer are decreased and so that the chips are arranged with predetermined spacings; and

sucking the chips 16 arranged with predetermined spacings one at a time by a suction collet 19 disposed above the chips so that the chips are separated from each other. The invention also provides an therefor. This method enables effective die bonding without damaging the chips.

Figure 1